

22. (Amended) An electronic component comprising:
a substrate with a plurality of contact nodes; and
a plurality of free-standing resilient interconnection elements coupled to the substrate in
such a manner that a base of an interconnection element electrically contacts a corresponding one
of the contact nodes and an interconnection element comprises:
a first element material adapted to be coupled to a substrate, and
a second element material coupled to the first element material,
wherein one of the first element material and the second element material comprises a
material having a transformable property such that upon transformation, a shape of the
interconnection element is modified, wherein the one of the first element material and the second
element material comprises a shape memory alloy.

48. (Twice Amended) An assembly comprising:
a first substrate having a plurality of first contact nodes formed on the first substrate and a
plurality of free-standing resilient interconnection elements coupled to the first substrate in such
a manner that a base of an interconnection element electrically contacts a corresponding one of
the first contact nodes; and
a second substrate having a plurality of second contact nodes,
wherein the interconnection element comprises:
a first element material adapted to be coupled to the first substrate, and
a second element material coupled to the first element material, and one of the
first element material and the second element material comprises a material having a
transformable property such that upon transformation, a geometric shape of the interconnection
element is modified,
wherein the interconnection element has a portion thereof which is capable of moving to
a first position in which the interconnection element is in contact with one of the plurality of
second contact nodes.

76. (Twice Amended) A system for contacting an electronic device including an assembly comprising:

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a first substrate having a plurality of first contact nodes formed on the first substrate and a plurality of free-standing resilient interconnection elements coupled to the first substrate in such a manner that a base of an interconnection element electrically contacts a corresponding one of the first contact nodes; and

a second substrate having a plurality of second contact nodes,
wherein the interconnection element comprises:

a first element material adapted to be coupled to the first substrate, and

a second element material coupled to the first element material, and one of the first element material and the second element material comprises a material having a transformable property such that upon transformation, a shape of the interconnection element is irreversibly modified, wherein the one of the first element material and the second element material comprises a shape memory alloy, and

wherein the interconnection element has a portion thereof which is capable of moving to a first position in which the interconnection element is in contact with one of the plurality of second contact nodes.